

TFA9894DUK(No Longer Manufactured)

Package [WLCSP48](#) WLCSP48, wafer level chip-scale package; 48 bumps; 0.4 mm pitch, 2.51 mm x 3.55 mm x 0.50 mm body



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Buy Options

TFA9894DUK/N2Z
 935373352062
 No Longer Manufactured
 REEL-Reel 7" Q1/T1 in Drypack
 Min. Package Quantity: 2000

Operating Characteristics

No information available

Environmental Information

Material Declaration	PbFree	EU RoHS	Halogen Free	RHF Indicator	REACH SVHC	Weight (mg)
TFA9894DUK/N2Z(935373352062)	Yes	Yes	Yes	D	REACH SVHC	9.587983282

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)		Peak Package Body Temperature (PPT) (C°)	
		Lead Soldering	Lead Free Soldering	Lead Soldering	Lead Free Soldering
TFA9894DUK/N2Z (935373352062)	No	1	1	240	260

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer
TFA9894DUK/N2Z (935373352062)	854233

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